

Assembly Bill of Materials

Texas Instruments

Project Name:	Cap Drop
Project File:	PMP9311.PrjPCB
Base ID:	PMP9311
Schematic Rev:	E1
Assembly Variant:	001
Build Quantity:	1
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Item	Designator	Description	RoHS	Manufacturer	PartNumber	Quantity	Required	Supplier 1				Alternate Manufacturer	Alternate PartNumber
1	PCB	Printed Circuit Board	Y	Any	PMP9311	1	1						
2	C1	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	Y	AVX	06035C104KAT2A	1	1	Digi-Key					
3	C2	CAP CER 22UF 100V 20% X7S SMD	Y	TDK	CKG57NX7S2A226M500JH	1	1	Digi-Key					
4	C3	CAP CER 10UF 50V 20% X7R 2220	Y	TDK	C5750X7R1H106M230KB	1	1						
5	C5	CAP, CERM, 22uF, 6.3V, +/-20%, X5R, 0805	Y	TDK	C2012X5R0J226M	1	1	Digi-Key					
6	C6	CAP, CERM, 10uF, 16V, +/-20%, X5R, 0603	Y	Taiyo Yuden	EMK107BBJ106MA-T	1	1	Digi-Key					
7	C7	CAP FILM 0.39UF 760VDC RADIAL	Y	EPCOS Inc	PHE840MD6390MD14R06L2	1	1	Digi-Key					
8	C8	CAP, AL, 220uF, 50V, +/-20%, 0.1 ohm, SMD	Y	Panasonic	EEVFK1H221P	1	1	Digi-Key					
9	D1	Diode, P-N, 1000V, 1A, SOD-123	Y	Comchip Technology	CGRM4007-G	1	1	Digi-Key					
10	D2, D2x	DIODE ZENER 20V 500MW SOD123	Y	Diodes Inc.	MMSZ5250B-7-F	2	2	Digi-Key					
11	D3	Diode, Schottky, 60V, 1A, SMA	Y	Diodes Inc.	B160-13-F	1	1	Digi-Key					
12	D4	Diode, Zener, 36V, 3W, SMA	Y	Micro Commercial	3SMAJ5938B-TP	1	1	Digi-Key					
13	EN, SW	Test Point, Miniature, White, TH	Y	Keystone	5002	2	2	Digi-Key					
14	FID1, FID2, FID3	Fiducial mark. There is nothing to buy or mount.	Y	N/A	N/A	3	3						
15	H1, H2, H3, H4	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Y	B&F Fastener Supply	NY PMS 440 0025 PH	4	4	Digi-Key					
16	H5, H6, H7, H8	Standoff, Hex, 0.5"L #4-40 Nylon	Y	Keystone	1902C	4	4	Digi-Key					
17	L1	Inductor, Shielded Drum Core, Ferrite, 220uH, 1.6A, 0.32 ohm, SMD	Y	Coilcraft	MSS1278-224KLB	1	1						
18	R1, R4, R5	RES, 1k ohm, 1%, 0.25W, 1206	Y	Yageo America	RC1206FR-071K02L	1	1	Digi-Key					
19	R6	RES, 200k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW0603200KFKEA	1	1	Digi-Key					
20	RB	RES, 10.0k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW060310K0FKEA	1	1	Digi-Key					
21	RT	RES, 33.2k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW060333K2FKEA	1	1	Digi-Key					
22	TP3, TP4	Test Point, Multipurpose, Black, TH	Y	Keystone	5011	2	2	Digi-Key					
23	U1	IC REG BUCK ADJ 0.6A TSOT23-6	Y	National Semiconductor	LM2842XMK	1	1	Digi-Key					
24	VI+, VI-, VO+, VO-	Terminal, Turret, TH, Double	Y	Keystone	1502-2	4	4	Digi-Key					
25	VIN	Test Point, Miniature, Red, TH	Y	Keystone	5000	1	1	Digi-Key					
26	DNP C4	CAP, CERM, 2700pF, 50V, +/-10%, X7R, 0805	Y	Kemet	C0805C272K5RACTU	0	0	Digi-Key					

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